

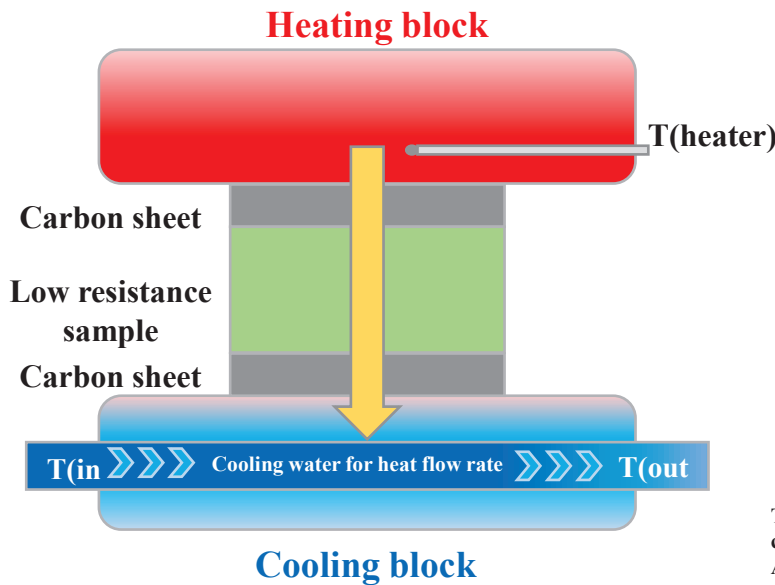
Thermoelectric Module Evaluation System in Air (F-CAL)

Evaluation of Heat Flow Rate of Thermal Resistance Substrate

Heat flow rate of 300W or more can be measured at 50°C or less!

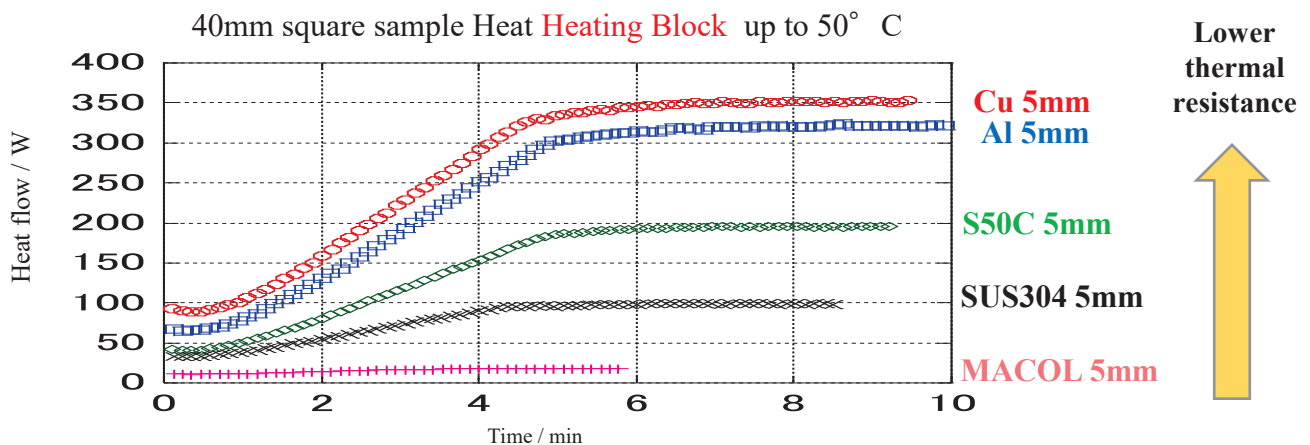
[Features]

- It is possible to evaluate Heat flow rate of low thermal resistance substrate in thickness direction.
- It is possible to convert thermal resistance with a reference sample known in thermal resistance (such as Cu• SUS304),
- It is possible to measure thermal resistance of a thin sheet material and metal bonded material



This system utilizes the results of research conducted by the National Institute of Advanced Industrial Science and Technology. (Patent No. WO 2017/164104)

[Measurement Examples]



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